Automotive Press-Fit Technology
Solderless Solutions

Connectors and Stacking Applications
Molded Sensor & Control Modules
Motor & Flapper Controls
Bus Bar Interconnects & Fuse Receptacles
Tire Pressure Monitors
Junction Boxes
Engine & Transmission Controllers

Interplex Industries, Inc.  І 14-34 110 Street, Suite 301  І  College Point, NY  11356
www.interplex.com/pressfit
Interplex’s Press-Fit, Solderless Interconnect Technology is designed and tested to meet standard automotive requirements for vibration, mechanical & thermal shock for temperatures up to 125°C, as defined by the IEC, EIA and SAE.

This technology allows for the assembly of a terminal or electrical lead to a printed circuit board’s (PCB) plated-through hole in such a way that an electrical mechanical connection is created and maintained without the application of solder.

**Interplex’s Press-Fit Solderless Technology Features:**

- Solderless Technology design & tested to meet automotive requirements
- Proven “Eye of the Needle” design
- Qualified to 125°C operational temperatures with optional 150°C alloys available
- Requirements defined by IEC, EIA and SAE
- Designs available for both .64mm and .80mm thick press-fit sections
- High conductive material options
- Compatible with various PCB plating types

**Press-Fit Sizes and Technology**

<table>
<thead>
<tr>
<th>Press-Fit Thickness</th>
<th>Alloy Options</th>
<th>Conductivity (IACS)</th>
<th>Nominal PCB Hole Size</th>
</tr>
</thead>
<tbody>
<tr>
<td>.64mm - Thick</td>
<td>Phosphor Bronze</td>
<td>13% to 15%</td>
<td>* 1.020 mm</td>
</tr>
<tr>
<td></td>
<td>Tinned Brass</td>
<td>25% to 30%</td>
<td></td>
</tr>
<tr>
<td>.80mm - Thick</td>
<td>Phosphor Bronze</td>
<td>13% to 15%</td>
<td>* 1.486 mm</td>
</tr>
<tr>
<td></td>
<td>Tinned Brass</td>
<td>25% to 30%</td>
<td></td>
</tr>
<tr>
<td></td>
<td>High Conductivity Alloy</td>
<td>75% to 80%</td>
<td></td>
</tr>
</tbody>
</table>

* Request “Application Drawings” for details and tolerances on PCB hole construction.
Advanced Engineered Press-Fit Solutions

The company’s Advanced Engineering team works with customers to develop press-fit solutions for applications such as discrete terminals and connect or assemblies, as well as custom-molded packages and specialized assemblies. In addition, Interplex leverages its expertise in product design, applications engineering, manufacturing and automation to help customers create the proper turnkey solution for any particular application.

Concept → Design → Prototype → Production

In addition, the company can leverage its global manufacturing resources to meet any regional manufacturing or automation requirements.

Summary Results of Mechanical and Environmental Tests

<table>
<thead>
<tr>
<th>Test Item</th>
<th>Acceptance Criteria</th>
<th>Testing for:</th>
<th>Result</th>
</tr>
</thead>
<tbody>
<tr>
<td>.64mm Insertion &amp; Retention Force</td>
<td>97N-Insertion-Max. 20N-Retention-Min.</td>
<td>• Forces in Upper &amp; Lower Limit Hole Sizes</td>
<td>Pass</td>
</tr>
<tr>
<td>.80mm Insertion &amp; Retention Force</td>
<td>178N-Insertion-Max. 62N-Retention-Min.</td>
<td>• Forces in Upper &amp; Lower Limit Hole Sizes</td>
<td>Pass</td>
</tr>
<tr>
<td>PTH Integrity</td>
<td>Per IEC 60352-5</td>
<td>• Deformation of Plated Through Hole</td>
<td>Pass</td>
</tr>
<tr>
<td>Random Vibration</td>
<td></td>
<td>• Movement of Contact Points</td>
<td>Pass</td>
</tr>
<tr>
<td>Thermal Shock</td>
<td></td>
<td>• Movement of Contact Points</td>
<td>Pass</td>
</tr>
<tr>
<td>Thermal Aging</td>
<td>Increase of Contact Resistance &lt; 3.0 mΩ Per IEC, EIA, SAE</td>
<td>• Stress Relaxation of Terminal and PCB • Growth of Oxide Film</td>
<td>Pass</td>
</tr>
<tr>
<td>Temp/Humidity Cycle</td>
<td></td>
<td>• Growth of Oxide Film</td>
<td>Pass</td>
</tr>
<tr>
<td>Mixing Flowing Gas</td>
<td></td>
<td>• Effectiveness of Barrier Plating</td>
<td>Pass</td>
</tr>
</tbody>
</table>

Detail Test “Summary Reports” Available on Request
**Interplex** is a vertically integrated global manufacturer of small precision parts and assemblies with over 25 worldwide locations in 10 Countries. Interplex offers complete solutions from concept through development and into scalable high volume production for almost any application requirement. Press-Fit sections can be designed into discrete metals stampings, molded and overmolded shrouds, housings and assemblies and/or incorporated into complete electronic and mechanical sub-assemblies.

### Interplex Global Locations

**Americas**
- California: Interplex Nascal
- Connecticut: Interplex Technologies
- Florida: Interplex Proto-Stamp
- Florida: Interplex Sunbelt
- Illinois: Interplex Daystar
- Kentucky: Interplex Plastics
- Massachusetts: Interplex Etch Logic
- Massachusetts: Interplex Metal Logic
- Michigan: Interplex Engineering Center
- New Jersey: Interplex NAS
- New Jersey: Interplex Precision Machining
- New York: Interplex Industries, Inc.
- Ohio: Interplex Medical
- Rhode Island: Interplex Automation
- Rhode Island: Interplex Engineereed Products
- Rhode Island: Interplex Metals
- Mexico: Interplex Mexico

**Europe**
- France: Interplex Soprec
- France: Interplex Microtech
- Germany: Interplex NAS GmbH
- Hungary: Interplex Hungary
- Scotland: Interplex PMP

**Asia**
- China: Interplex Electronics (Dalian)
- China: Interplex Electronics (Hangzhou)
- China: Interplex Stewart EFI
- India: Interplex Electronics India
- Korea: Interplex Quantum
- Malaysia: Interplex Electronics Malaysia
- Singapore: Interplex Singapore

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